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September 2016

### FDB0630N1507L

# N-Channel PowerTrench® MOSFET **150 V, 130 A, 6.4 m** $\Omega$

#### **Features**

- Max  $r_{DS(on)}$  = 6.4 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 18 A
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low
- High Power and Current Handling Capability
- RoHS Compliant

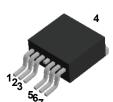


#### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been especially tailored to minimize the on-state resistance while maintaining superior ruggedness and switching performance for industrial applications.

#### **Applications**

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch



1. Gate

2. Source/Kelvin Sense

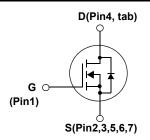
3. Source/Kelvin Sense

4. Drain

5. Source

6. Source 7. Source

D2-PAK (TO263)



### **MOSFET Maximum Ratings** $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter			Ratings	Units
$V_{DS}$	Drain to Source Voltage			150	V
$V_{GS}$	Gate to Source Voltage			±20	V
I <sub>D</sub>	Drain Current -Continuous	T <sub>C</sub> = 25°C	(Note 5)	130	
	-Continuous	T <sub>C</sub> = 100°C	(Note 5)	90	Α
	-Pulsed		(Note 4)	720	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	693	mJ
В	Power Dissipation	T <sub>C</sub> = 25°C		300	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	3.8	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera	ture Range		-55 to +150	°C

#### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	40	C/VV

#### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB0630N1507L	FDB0630N1507L	D2-PAK-7L	330mm	24mm	800 units

# **Electrical Characteristics** $T_J$ = 25 °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25 °C		92		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	2.9	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-13		mV/°C
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 18 \text{ A}$		4.9	6.4	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 18 \text{ A}$		63		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V - 75 V V - 0 V	7065	9895	pF
Coss	Output Capacitance	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, f = 1 MHz	552	775	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	27	50	pF
$R_q$	Gate Resistance		2.5		Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		33	52	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 18 A,	31	53	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{GEN}$ = 6 $\Omega$	60	96	ns
t <sub>f</sub>	Fall Time		17	30	ns
$Q_{g}$	Total Gate Charge	V 75 V L 40 A	97	135	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 18 A, V <sub>GS</sub> = 10 V	30		nC
$Q_{gd}$	Gate to Drain "Miller" Charge	VGS - 10 V	17		nC

#### **Drain-Source Diode Characteristics**

$I_S$	Maximum Continuous Drain to Source Diode Forward Current			130	Α
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current			720	Α
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 18 \text{ A}$ (Note 2)	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>E</sub> = 18 A, di/dt = 100 A/μs	107	172	ns
Q <sub>rr</sub>	Reverse Recovery Charge	ης – 10 A, αιναι – 100 Ανμδ	229	366	nC

 $R_{0JG}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{0JG}$  is guaranteed by design while  $R_{0GA}$  is determined by the user's board design.

a) 40 °C/W when mounted on a 1 in  $^2$  pad of 2 oz copper. b) 62.5 °C/W when mounted on a minimum pad of 2 oz copper.

<sup>2.</sup> Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0 %.

<sup>3.</sup>  $E_{AS}$  of 693 is based on starting  $T_J$  = 25 °C, L = 0.3 mH,  $I_{AS}$  = 68 A,  $V_{DD}$  = 135 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH,  $I_{AS}$  = 99 A.

<sup>4.</sup> Pulsed Id please refer to Figure "Forward Bias Safe Operating Area" for more details.

<sup>5.</sup> Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

#### **Typical Characteristics** $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted.

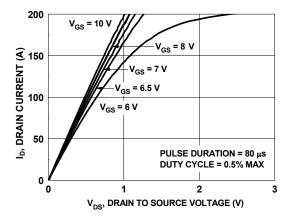


Figure 1. On Region Characteristics

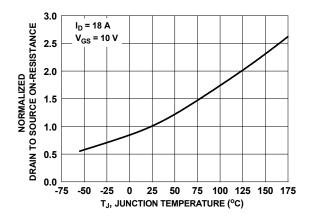


Figure 3. Normalized On Resistance vs. Junction Temperature

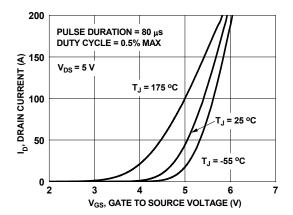


Figure 5. Transfer Characteristics

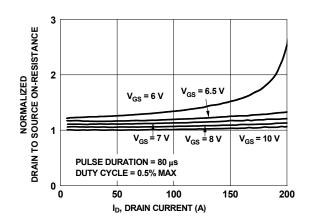


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

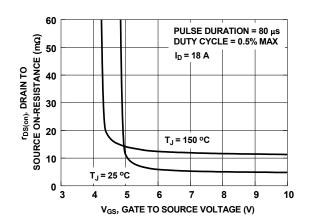


Figure 4. On-Resistance vs. Gate to Source Voltage

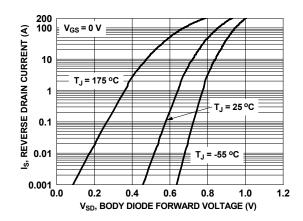


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

### **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

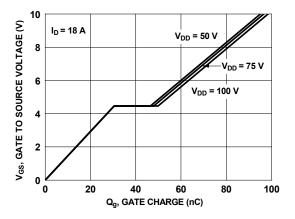


Figure 7. Gate Charge Characteristics

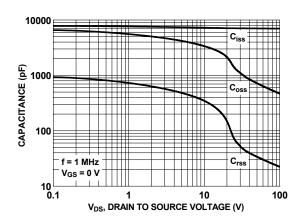


Figure 8. Capacitance vs. Drain to Source Voltage

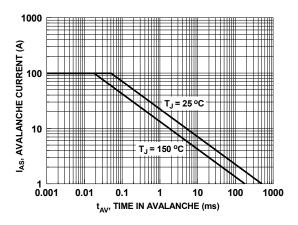


Figure 9. Unclamped Inductive Switching Capability

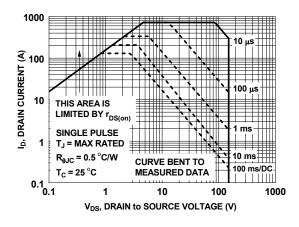


Figure 10. Forward Bias Safe Operating Area

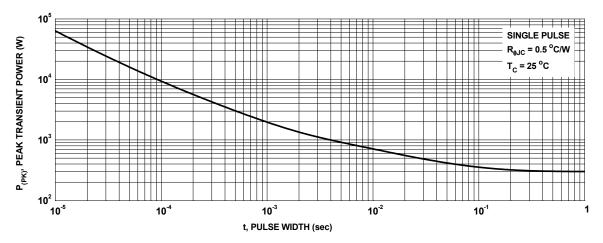


Figure 11. Single Pulse Maximum Power Dissipation

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

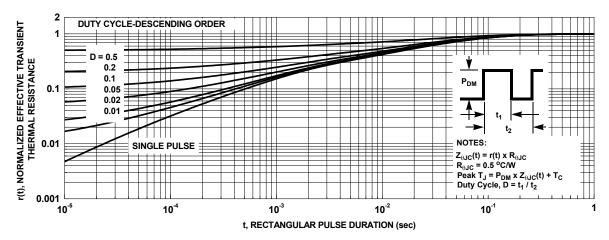
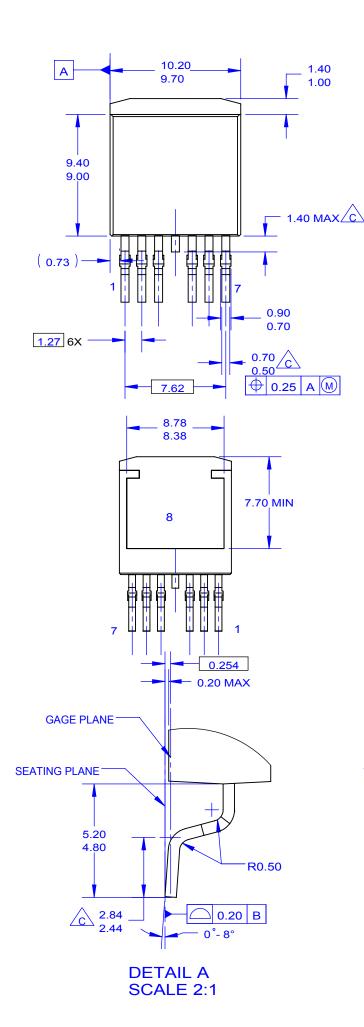
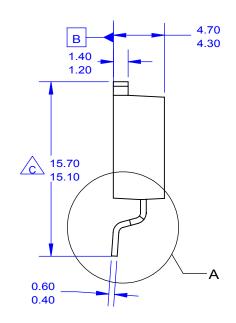


Figure 12. Junction-to-Case Transient Thermal Response Curve



(10.50) (8.40) (10,20) (3.45)(0.95) (1.27) 6X (7.62)

#### LAND PATTERN RECOMMENDATION



#### NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.
- OUT OF JEDEC STANDARD VALUE.
  D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
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